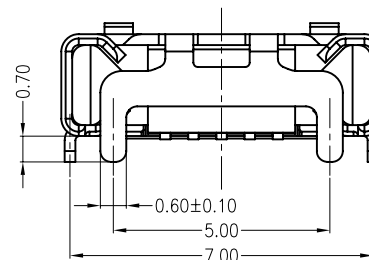
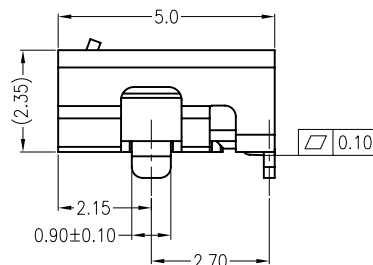
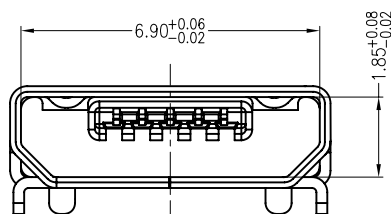
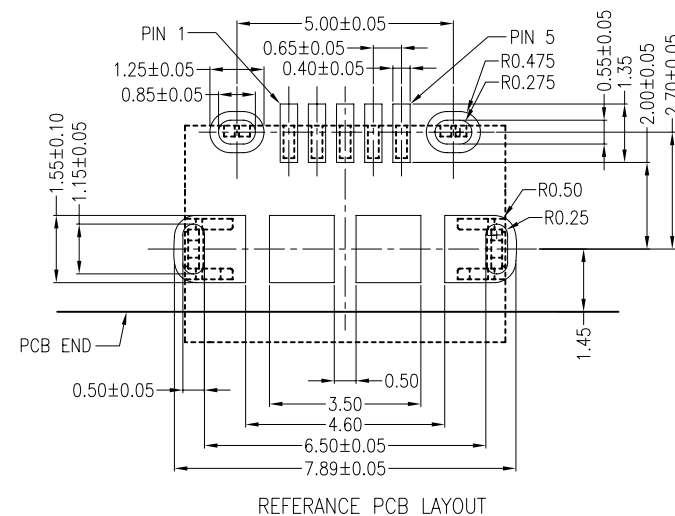
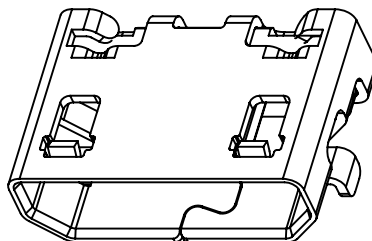
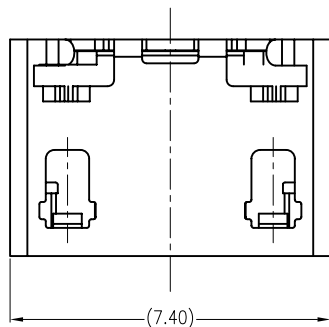


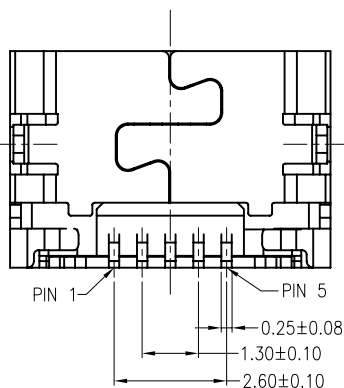
THE PART MEETS TECONN "GP001" COMPLIANCE



A4A0505-C-XX-R

Mating Area plating

- 01: Au 1u"Min.
- 03: Au 3u"Min.
- 05: Au 5u"Min.
- 10: Au 10u"Min.
- 15: Au 15u"Min.
- 30: Au 30u"Min.



- 1.Contact Resistance:30mOHM Max.;
- 2.Dielectric Withstanding Voltage:100V AC For 1 Minute;
- 3.Insulation Resistance:1000M OHM Min.;
- 4.Mating And Unmating Force:
Mating Force:35N Max/Unmating Force:8N Min;
- 5.Durability:10000 Cycles;

Item	Title	Material	Dispose
1	Shell	Stainless Steel	Matte Tin 50u"(min.)
2	Terminal	Copper Alloy	Mating Area:See P/N Solder Tails:G/F
3	InsertMolding	LCP	UL94V-0

X. ± 0.35	APPD:	TITLE: Micro B Rec.Shell Dip	 泰康电子 TECONN		
.X ± 0.25	CHKD:			PART NO: A4A0505-C-XX-R	
.XX ± 0.15					
.XXX±					
X° ± 2°	DR:				
.X° ± 1.5°					
	UNITS: mm	SCALE: 1:1	DWG NO: C-A4A0505-C-XX-R	CUSTOMER DRAWING	SHEET:1OF
					REV: A

A	TE2011-0017	New Drawing	2011/04/26
REV	ECN NO	DESCRIPTION	DATE